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## IN THE UNITED STATES PATENT &amp; TRADEMARK OFFICE



Application Number : 10/811,152 Confirmation No. 8475  
 Applicant : Ga Won LEE  
 Filed : March 29, 2004  
 Tech Cntr/AU : 2812  
 Examiner : Lynne Ann Gurley  
 Entitled : METHOD OF FORMING INTER-DIELECTRIC LAYER IN SEMICONDUCTOR DEVICE  
 Attorney Reference : 123034-05004767  
 Customer Number : 43569

**MAIL STOP AMENDMENT**

Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, Virginia 22313-1450

**AMENDMENT/RESPONSE TRANSMITTAL**

Transmitted herewith is an amendment/response for this application.

**EXTENSION OF TIME**

A petition for extension of time under 37 C.F.R. 1.136 is not believed necessary.

**CLAIM FEES**

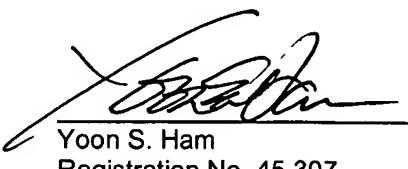
The claim fees have been calculated as follows:

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total	12	-	20	= 0 x \$ 50.00	= \$ 0.00
Independent	3	-	3	= 0 x \$ 200.00	= \$ 0.00
FIRST PRESENTATION OF MULTIPLE DEP. CLAIM+			\$ 360.00	= \$	<u>0.00</u>
TOTAL ADDITIONAL CLAIM FEE DUE				\$	0.00

**FEE PAYMENT**

Authorization is given herein to charge the any deficiencies in the fees not specifically authorized herein, or to further credit any overpayments, to Deposit Account No. 503-121 in order to maintain the pendency of this application.

Intellectual Property Department  
 Mayer Brown Rowe & Maw LLP  
 1909 K Street, N.W.  
 Washington, D.C. 20006-1101

  
 Yoon S. Ham  
 Registration No. 45,307  
 (202) 263-3280

Date: May 15, 2006

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**RESPONSE UNDER 37 C.F.R. § 1.111**

Sir:

Responsive to the Office Action mailed February 15, 2006, Applicant herewith submits the following amendments and remarks.